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Front Matter: Volume 9427

, "Front Matter: Volume 9427," Proc. SPIE 9427, Design-Process-Technology
Co-optimization for Manufacturability IX, 942701 (22 April 2015); doi:
10.1117/12.2193828

Event: SPIE Advanced Lithography, 2015, San Jose, California, United States

PROCEEDINGS OF SPIE

Design-Process-Technology Co-optimization for Manufacturability IX

**John L. Sturtevant
Luigi Capodieci**
Editors

**25–26 February 2015
San Jose, California, United States**

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Published by
SPIE

Volume 9427

Proceedings of SPIE 0277-786X, V. 9427

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Design-Process-Technology Co-optimization for Manufacturability IX, edited by John L. Sturtevant, Luigi Capodieci,
Proc. of SPIE Vol. 9427, 942701 · © 2015 SPIE · CCC code: 0277-786X/15/\$18 · doi: 10.1117/12.2193828

Proc. of SPIE Vol. 9427 942701-1

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Author(s), "Title of Paper," in *Design-Process-Technology Co-optimization for Manufacturability IX*, edited by John L. Sturtevant, Luigi Capodieci, Proceedings of SPIE Vol. 9427 (SPIE, Bellingham, WA, 2015) Article CID Number.

ISSN: 0277-786X

ISBN: 9781628415292

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445

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Printed in the United States of America.

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